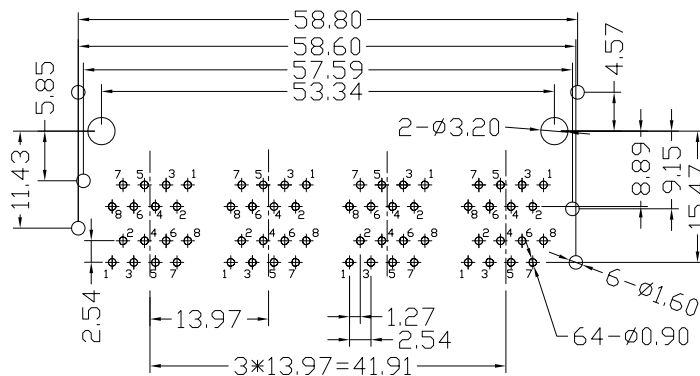
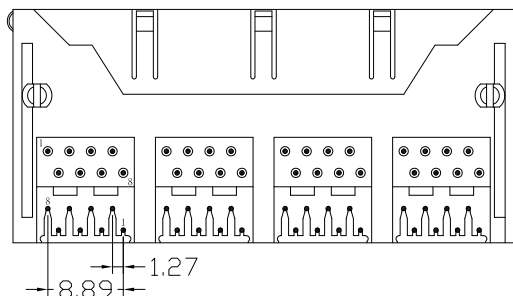
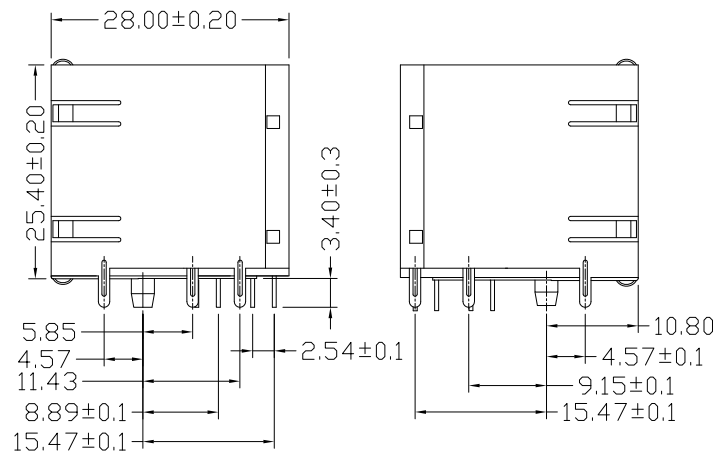
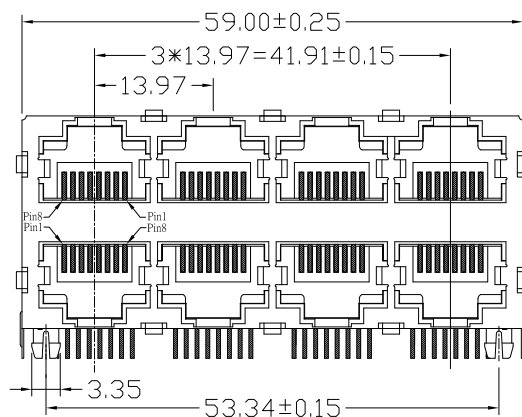


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2015/07/09	Phebe Su



PCB LAYOUT



SPECIFICATION:

Electrical:

Current Rating:1.5Amp max @25°C

Voltage Rating: 150VAC max

Insulation Resistance: 500 megohms min

Contact Resistance:30 milliohms max

Withstanding Voltage:1000 VAC

Mechanical:

Durability: 750 Cycles

Operating Temperature: -40°C ~ +70°C

Storage Temperature: -50°C~+75°C

Contact Normal Force:100g Minimum

Material:

Housing:High Temperature Thermoplastic UL94V-0 PBT BLACK

Shield: 0.15mm Thickness Copper Alloy Ni Plated

Contact:0.45mm Dia Phosphor Bronze Plated G/F Over Ni

Soldering Temperature: 260+/-5°C, 5sec/95%Area be covered

Withstand Temperature: 220+/-5°C, 5sec No stick tin melting phenomenon

MATRIX PART NO:

M R J N - 2 4 T 346 R S

Matrix-RJ45—

F : 10/100

G : 10/100/1000

N : Pure Connector

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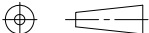
11:1X1 ; 21:2X1—
12:1X2 ; 22:2X2
14:1X4 ; 24:2X4
16:1X6 ; 26:2X6
18:1X8 ; 28:2X8
1U:RJ+USB

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RS : ROHS
—HF : Halogen Free

—Series Number

—S : SMD
T : THT

NO	VARIETY	QTY	MATERIAL	REMARK	
 Matrix Electronics Co.,Ltd					
TOLERANCE: X.X ±0.25 X.XX ±0.15 X.XXX ±0.10 ANGLE: ±3°		DESIGN BY :	DATE :	PART NAME:	
		Phebe Su	2015/07/09	RJ45 2X4 PCB JACK	
		CHECKED BY:	DATE :	PART NO.	MRJN-24T346RS
		Vicky Hsieh	2015/07/09		
		APPROVED BY1:	DATE :	MOLD NO.	NA
UNIT: mm [inch]		Richard Hsieh	2015/07/09		
		APPROVED BY2:	DATE :	DRAW NO.	
		Richard Hsieh	2015/07/09	SHEET NO.	1 OF 1